

## OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

Check for Samples: [SN74LV541AT](#)

### FEATURES

- Inputs Are TTL-Voltage Compatible
- 4.5-V to 5.5-V  $V_{CC}$  Operation
- Typical  $t_{pd}$  of 4 ns at 5 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  
<0.8 V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  
>2.3 V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- Supports Mixed-Mode Voltage Operation on All Ports
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

### DESCRIPTION

The SN74LV541AT is designed for 4.5-V to 5.5-V  $V_{CC}$  operation. The inputs are TTL-voltage compatible, which allows them to be interfaced with bipolar outputs and 3.3-V devices. The device also can be used to translate from 3.3 V to 5 V.

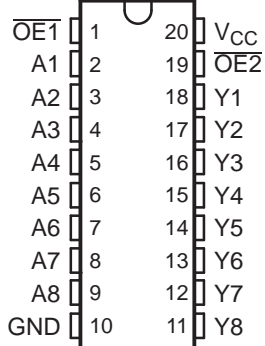
This device is ideal for driving bus lines or buffer memory address registers. It features inputs and outputs on opposite sides of the package to facilitate printed circuit board layout.

The 3-state control gate is a two-input AND gate with active-low inputs so that, if either output-enable ( $\overline{OE1}$  or  $\overline{OE2}$ ) input is high, all corresponding outputs are in the high-impedance state. The outputs provide noninverted data when they are not in the high-impedance state.

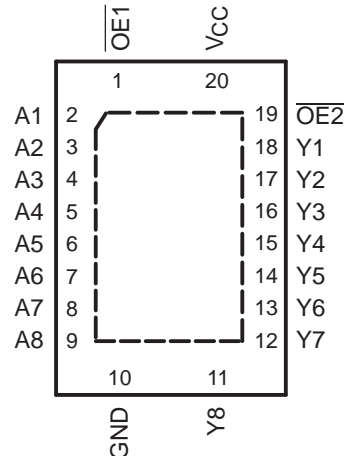
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  shall be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

DB, DGV, DW, NS, OR PW PACKAGE  
(TOP VIEW)



RGY PACKAGE  
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



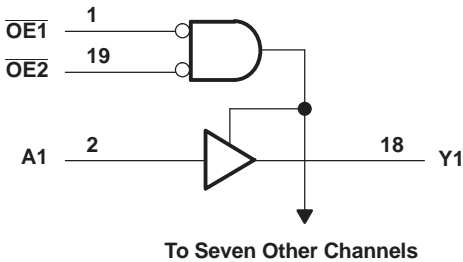
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

**FUNCTION TABLE  
(EACH BUFFER/DRIVER)**

INPUTS			OUTPUT Y
$\overline{OE1}$	$\overline{OE2}$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

**LOGIC DIAGRAM (POSITIVE LOGIC)**



## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	–0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	7	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	7	V
$V_O$	Output voltage range applied in the high or low state <sup>(2)(3)</sup>	–0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$		–20 mA
$I_{OK}$	Output clamp current	$V_O < 0$		–50 mA
$I_O$	Continuous output current	$V_O = 0$ to $V_{CC}$		±35 mA
	Continuous current through $V_{CC}$ or GND			±70 mA
$\theta_{JA}$	Package thermal impedance	DB package <sup>(4)</sup>		70
		DGV package <sup>(4)</sup>		92
		DW package <sup>(4)</sup>		58
		NS package <sup>(4)</sup>		60
		PW package <sup>(4)</sup>		83
		RGY package <sup>(5)</sup>		37
$T_{stg}$	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7
- (5) The package thermal impedance is calculated in accordance with JESD 51-5.

## RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 4.5$ V to 5.5 V		2
$V_{IL}$	Low-level input voltage	$V_{CC} = 4.5$ V to 5.5 V		0.8
$V_I$	Input voltage	0	5.5	V
$V_O$	Output voltage	High or low state		0 $V_{CC}$
		3-state		0 5.5
$I_{OH}$	High-level output current	$V_{CC} = 4.5$ V to 5.5 V		–16 mA
$I_{OL}$	Low-level output current	$V_{CC} = 4.5$ V to 5.5 V		16 mA
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 4.5$ V to 5.5 V		20 ns/V
$T_A$	Operating free-air temperature	–40	125	°C

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = –40°C to 85°C		T <sub>A</sub> = –40°C to 125°C			UNIT
								Recommended			
			SN74LV541AT			SN74LV541AT		SN74LV541AT			
			MIN	TYP	MAX	MIN	MAX	MIN	TYP	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = –50 μA	4.5 V	4.4	4.5		4.4		4.4			V
	I <sub>OH</sub> = –16 mA	4.5 V	3.8			3.8		3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	4.5 V		0	0.1		0.1			0.1	V
	I <sub>OL</sub> = 16 mA	4.5 V			0.55		0.55			0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±0.1		±1			±1	μA
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V			±0.25		±2.5			±2.5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			2		20			20	μA
ΔI <sub>CC</sub> <sup>(1)</sup>	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5			150	mA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0			0.5		5			5	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND			2							pF

(1) This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			T <sub>A</sub> = –40°C to 85°C		T <sub>A</sub> = 25°C to 125°C			UNIT
				MIN	TYP	MAX	MIN	MAX	Recommended			
									MIN	TYP	MAX	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 15 pF	2.6	5	6.9	1	8	1		9	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y		3	8.3	11.3	1	13	1		14	
t <sub>dis</sub>	$\overline{\text{OE}}$	Y		1.4	3.9	7.5	1	8	1		8.5	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 50 pF	4	5.5	7.9	1	9	1		10	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y		3.8	8.8	12.3	1	14	1		15.2	
t <sub>dis</sub>	$\overline{\text{OE}}$	Y		2.1	9.4	11.9	1	13.5	1		14	
t <sub>sk(o)</sub>						1		1				

## NOISE CHARACTERISTICS<sup>(1)</sup>

V<sub>CC</sub> = 5 V, C<sub>L</sub> = 50 pF

PARAMETER		T <sub>A</sub> = 25°C			UNIT
		MIN	TYP	MAX	
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		1.1	1.5	V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		–1.1	–1.5	V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>		4		V
V <sub>IH(D)</sub>	High-level dynamic input voltage		2		V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.8	V

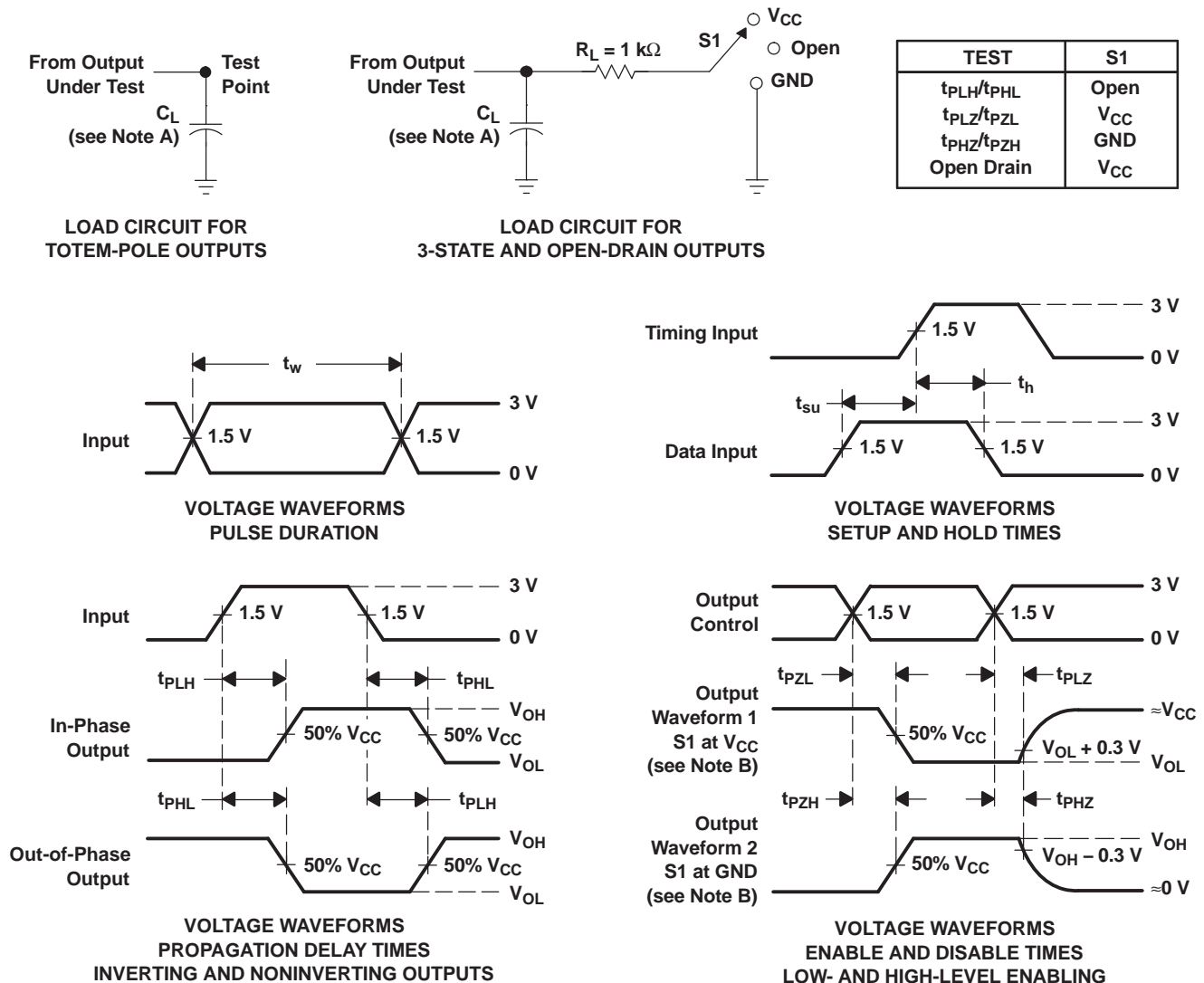
(1) Characteristics are for surface-mount packages only.

## OPERATING CHARACTERISTICS

V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	Outputs enabled C <sub>L</sub> = 50 pF, f = 10 MHz	8	pF

## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuits and Voltage Waveforms**

REVISION HISTORY

Changes from Revision A (August 2005) to Revision B	Page
• Added parameter values for –40 to 125°C temperature ratings. ....	<a href="#">4</a>

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74LV541ATDBR</a>	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
SN74LV541ATDBR.A	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
<a href="#">SN74LV541ATDGVR</a>	Active	Production	TVSOP (DGV)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
SN74LV541ATDGVR.A	Active	Production	TVSOP (DGV)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
<a href="#">SN74LV541ATDW</a>	Obsolete	Production	SOIC (DW)   20	-	-	Call TI	Call TI	-40 to 125	LV541AT
<a href="#">SN74LV541ATDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
SN74LV541ATDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
<a href="#">SN74LV541ATNSR</a>	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV541AT
SN74LV541ATNSR.A	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV541AT
<a href="#">SN74LV541ATPW</a>	Obsolete	Production	TSSOP (PW)   20	-	-	Call TI	Call TI	-40 to 125	LV541AT
<a href="#">SN74LV541ATPWR</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
SN74LV541ATPWR.A	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
SN74LV541ATPWR.B	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV541AT
<a href="#">SN74LV541ATPWT</a>	Obsolete	Production	TSSOP (PW)   20	-	-	Call TI	Call TI	-40 to 125	LV541AT
<a href="#">SN74LV541ATRGYR</a>	Active	Production	VQFN (RGY)   20	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	VV541
SN74LV541ATRGYR.A	Active	Production	VQFN (RGY)   20	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	VV541

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV541ATDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LV541ATDGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV541ATDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LV541ATNSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LV541ATPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LV541ATRGYR	VQFN	RGY	20	3000	330.0	12.4	3.71	4.71	1.1	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV541ATDBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74LV541ATDGVR	TVSOP	DGV	20	2000	353.0	353.0	32.0
SN74LV541ATDWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74LV541ATNSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74LV541ATPWR	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74LV541ATRGYR	VQFN	RGY	20	3000	353.0	353.0	32.0



4214851/B 08/2019

## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## GENERIC PACKAGE VIEW

**RGY 20**

**VQFN - 1 mm max height**

3.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FGLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

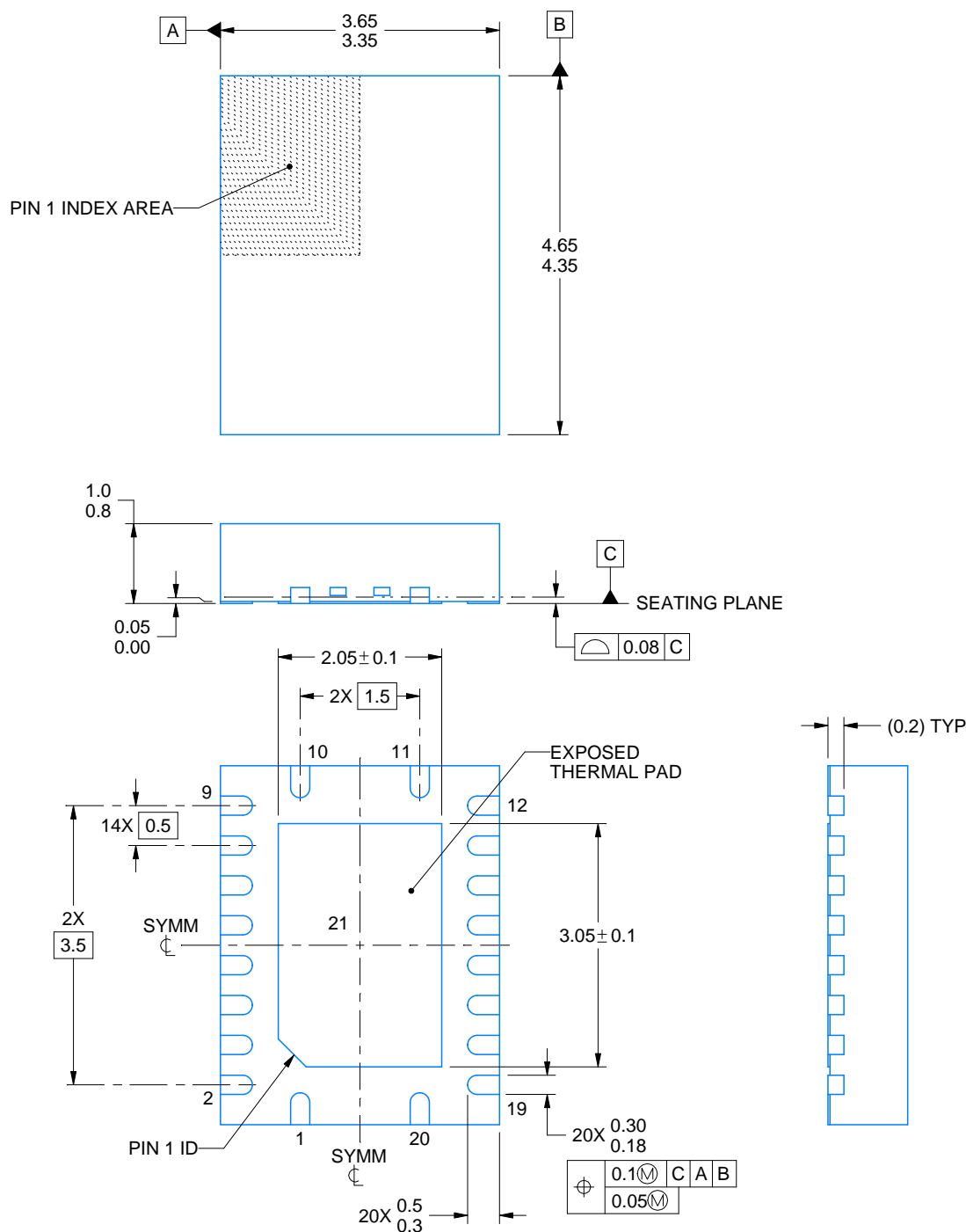


4225264/A



**VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



4225320/A 09/2019

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

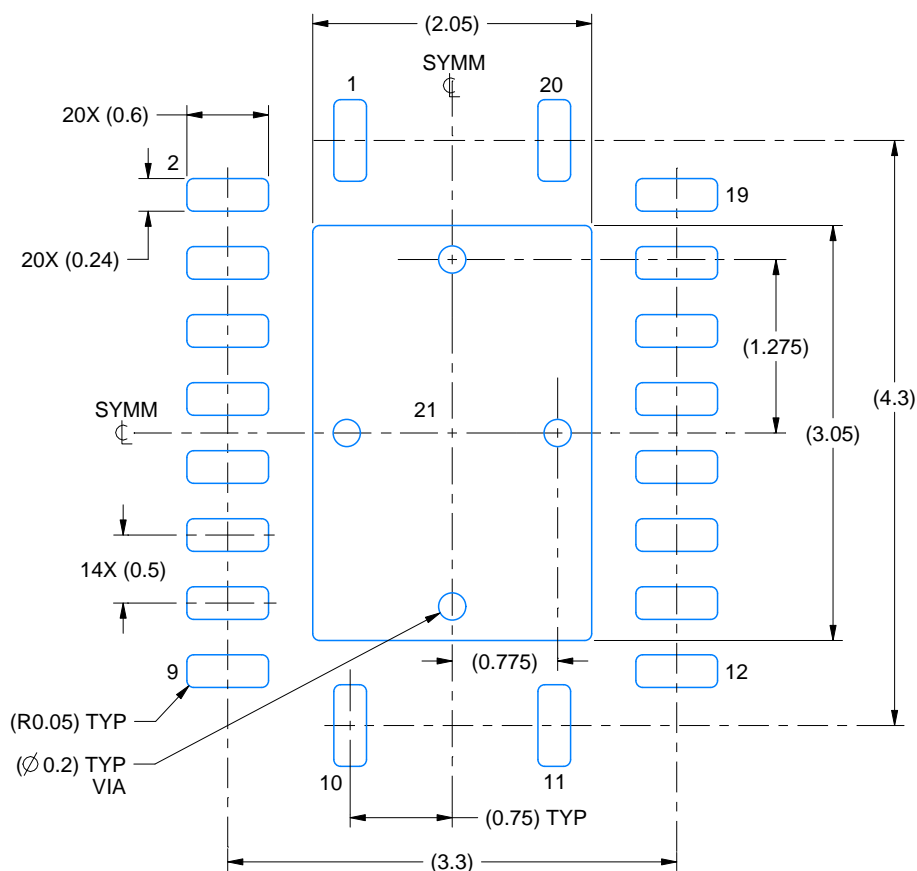


# EXAMPLE BOARD LAYOUT

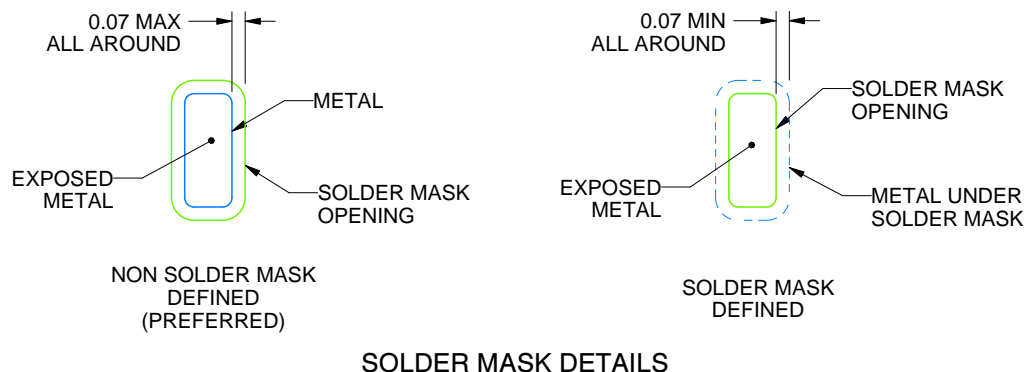
RGY0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



4225320/A 09/2019

NOTES: (continued)

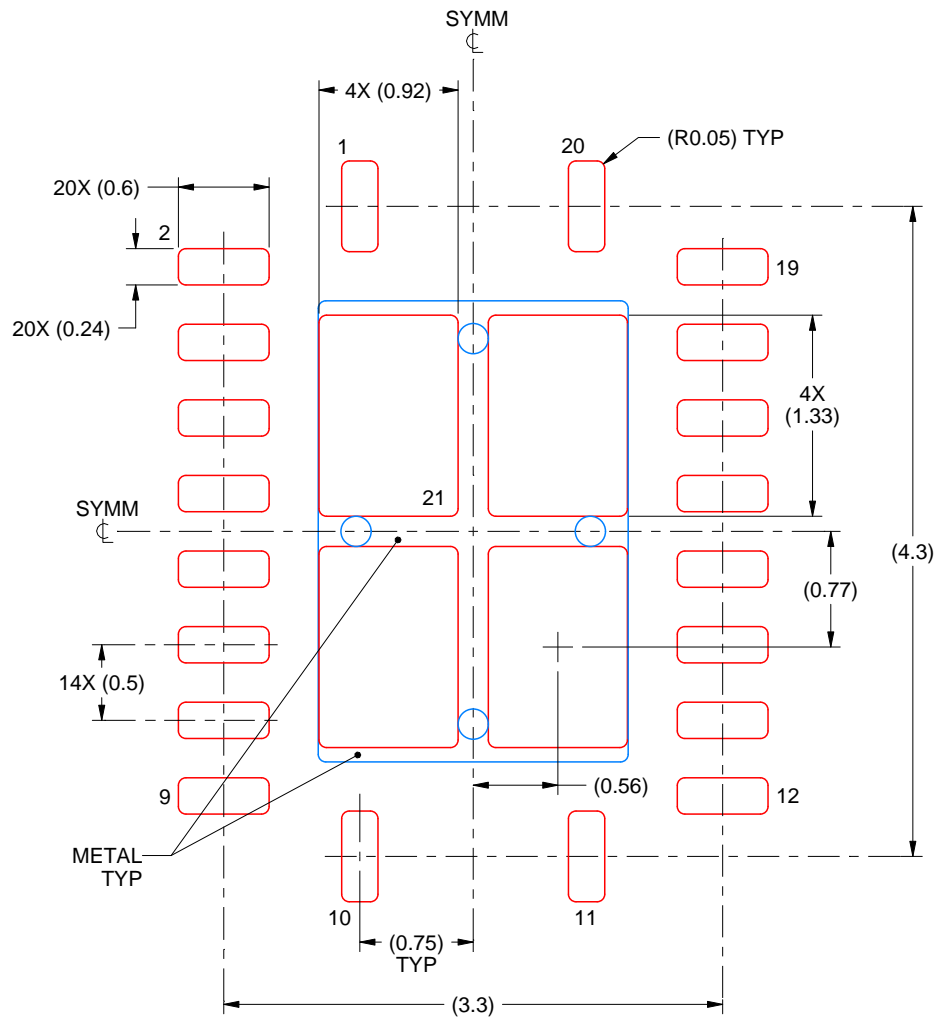
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RGY0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 21  
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:20X

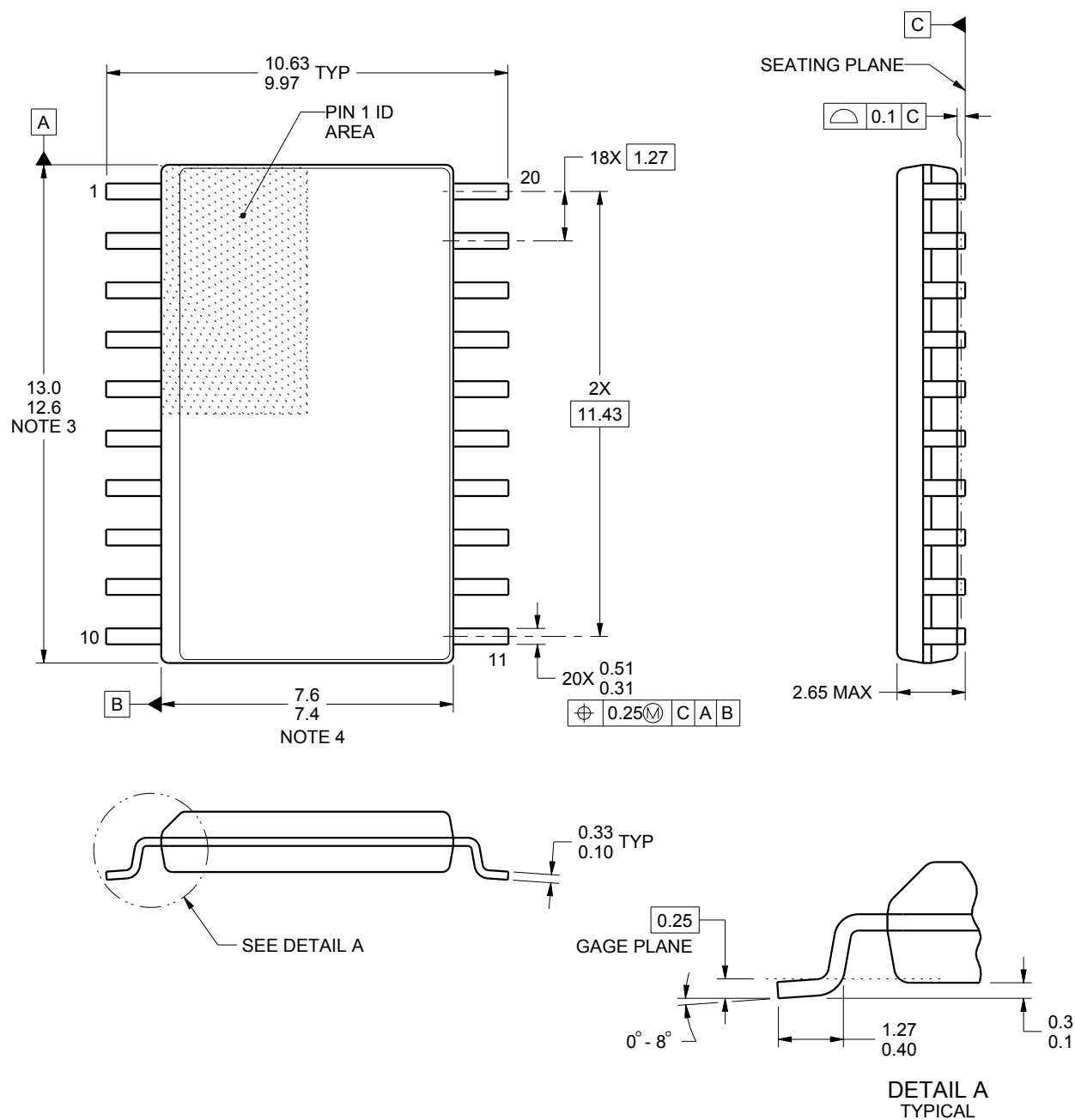
4225320/A 09/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

**DW0020A****PACKAGE OUTLINE****SOIC - 2.65 mm max height**

SOIC



4220724/A 05/2016

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

**DW0020A**

## SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



## SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.  
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



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